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2024 3rd International Conference on Artificial Intelligence, Internet of Things and Cloud Computing Technology, AIoTC 2024

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Abstract

The proceedings contain 81 papers. The topics discussed include: research on distributed computing power scheduling based on ant path optimization; facial expression recognition in museum settings using an enhanced residual networks; LSD3K: a benchmark for smoke removal from laparoscopic surgery images; enhancing single image de-raining with a sparse spatial transformer; research on image recognition and intelligent management of accounting bills based on information technology; cloud-based flight test data management and application platform; design and simulation of biped robot based on ball screw; thinking about anti-drone strategies; REmbed: a knowledge graph embedding model integrating dual-prediction and graph attention networks; and improving the CodeGeeX model based on the relative convolutional multi-head attention method.

Conference Information



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Feedback

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